

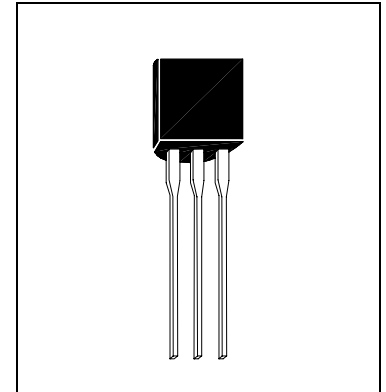


HMP5A55

PNP SILICON TRANSISTOR

Description

The HMP5A55 is designed for using in a amplifier applications.



Absolute Maximum Ratings

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 - Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 - V_{CB0} Collector to Base Voltage -60 V
 - V_{CEO} Collector to Emitter Voltage -60 V
 - V_{EB0} Emitter to Base Voltage -4 V
 - I_C Collector Current -500 mA

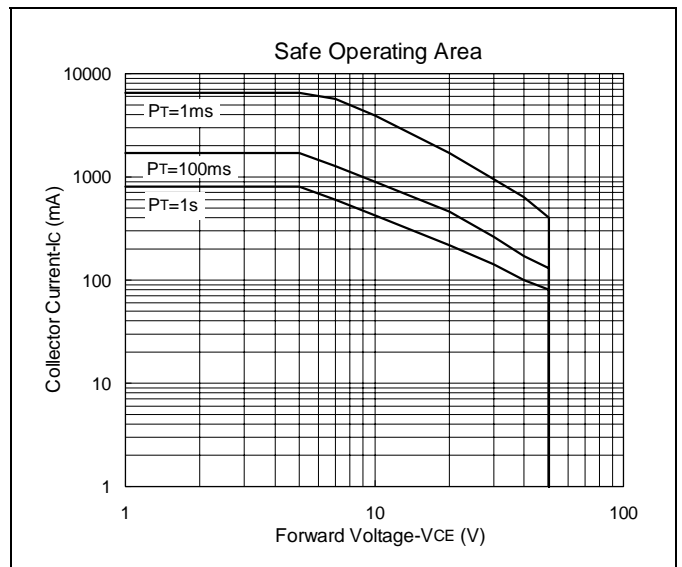
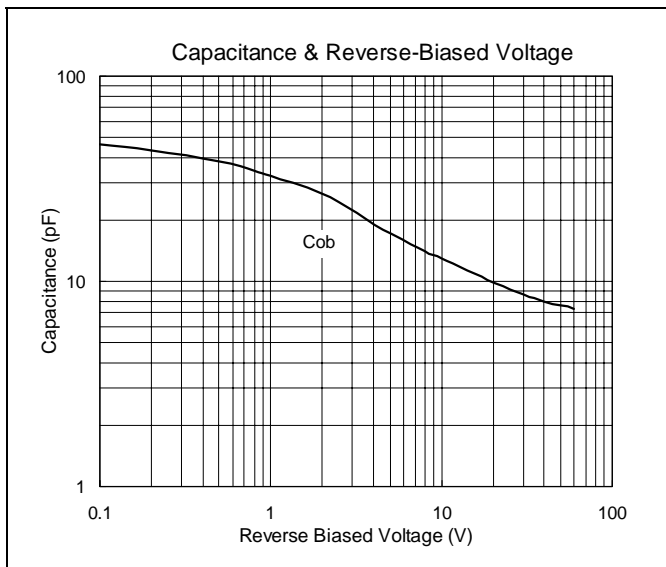
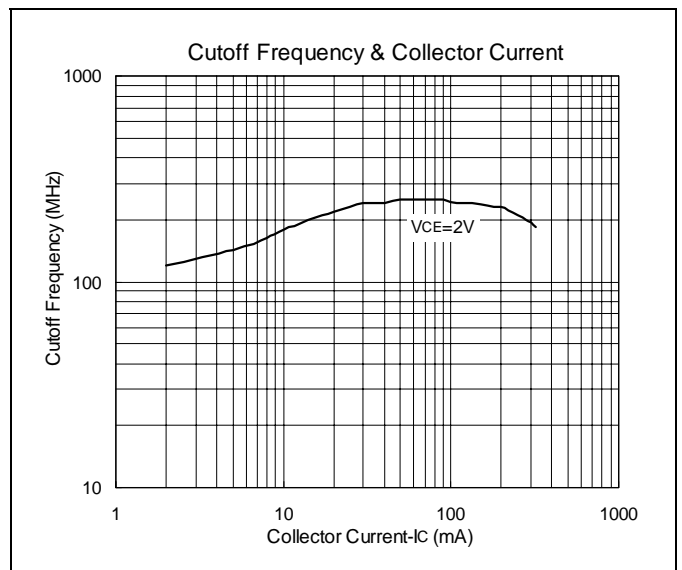
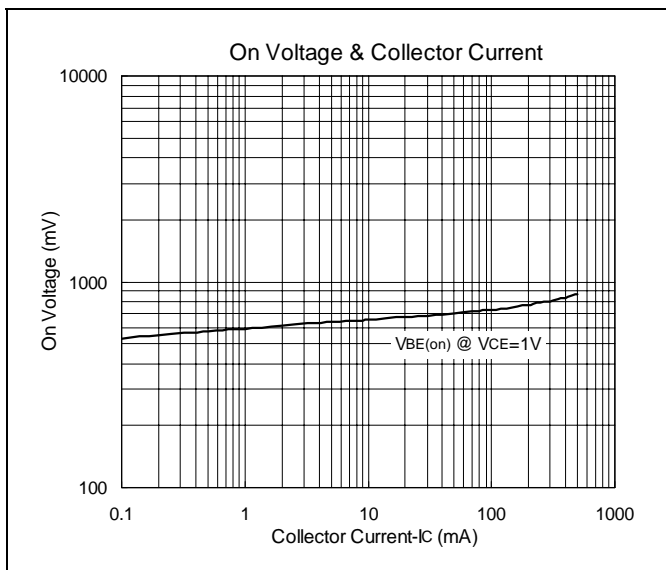
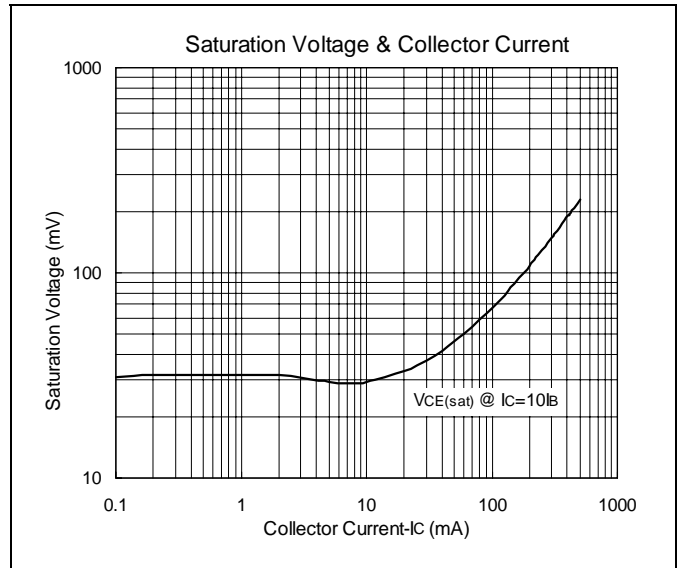
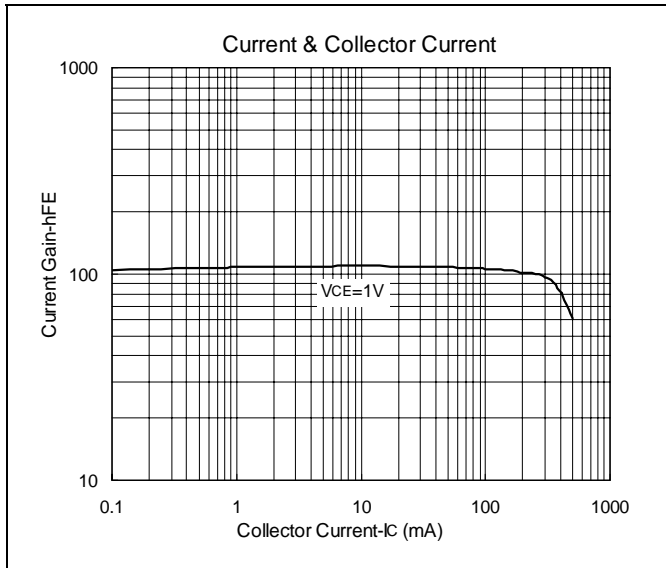
Characteristics (Ta=25°C)

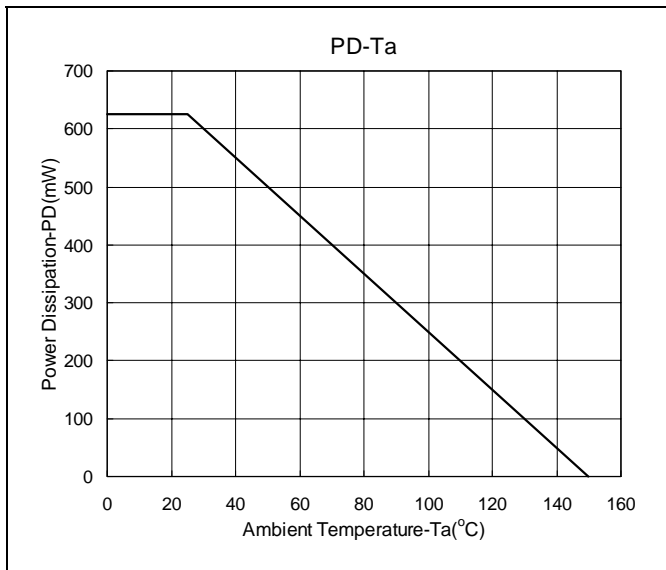
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
B _V C _{B0}	-60	-	-	V	I _C =-100uA, I _E =0
B _V C _{EO}	-60	-	-	V	I _C =-1mA, I _B =0
B _V E _{B0}	-4	-	-	V	I _E =-100uA, I _C =0
I _C B ₀	-	-	-100	nA	V _{CB} =-60V, I _E =0
I _C E ₀	-	-	-100	nA	V _{CE} =-60V, I _B =0
*V _{CE} (sat)	-	-	-0.25	V	I _C =-100mA, I _B =-10mA
V _{BE} (on)	-	-	-1.2	V	I _C =-100mA, V _{CE} =-1V
*h _{FE} 1	50	-	-		I _C =-10mA, V _{CE} =-1V
*h _{FE} 2	50	-	-		I _C =-100mA, V _{CE} =-1V
f _T	50	-	-	MHz	I _C =-100mA, V _{CE} =-1V, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



Characteristics Curve







TO-92 Dimension

3-Lead TO-92 Plastic Package
HSMC Package Code : A

Marking :

HSMC Logo → □ □ □ □ ← Product Series
 Part Number → □ □ □ □ □ □
 Date Code → □ □ □ □ □ □ ← Rank
 Laser Mark

HSMC Logo
 Product Series
 Part Number → □ □ □ □ □ □
 Ink Mark

Style : Pin 1. Emitter 2. Base 3. Collector

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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